

Title (en)

METHOD FOR MAKING CONTACT WITH A COMPONENT EMBEDDED IN A PRINTED CIRCUIT BOARD

Title (de)

VERFAHREN ZUM KONTAKTIEREN EINES IN EINE LEITERPLATTE EINGEBETTETEN BAUELEMENTS SOWIE LEITERPLATTE

Title (fr)

PROCÉDÉ DE CONNEXION ÉLECTRIQUE D'UN COMPOSANT INCORPORÉ DANS UN CIRCUIT IMPRIMÉ AINSI QUE CIRCUIT IMPRIMÉ

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Application

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Abstract (en)

[origin: WO2015127489A1] The invention relates to a method for making contact with a component (6) embedded in a printed circuit board (13), which method has the following steps: a) providing a core (1) which has at least one insulating layer (2) and at least one conductor layer (3, 4) applied to the insulating layer (2), b) embedding at least one component (6) in a depression (5) in the insulating layer (2), wherein the contact pins (8) of the component (6) are located substantially in the plane of an outer surface of the core (1) having the at least one conductor layer (4), c) applying a varnish (9) that can be photo-structured to the one outer surface of the core (1) on which the component (6) is arranged, filling the spaces between the contact pins (8) of the component (6), d) exposing end faces of the contact pins (8) and the regions of the conductor layer (4) covered by the varnish (9) that can be photo-structured, by illuminating and developing the varnish (9) that can be photo-structured, e) by applying a semi-additive process, depositing a layer (10) of conductor material on the exposed end faces of the contact pins (8) and the exposed regions of the conductor layer (4), and forming a conductor structure (12-12), at least on the one outer surface of the core (1) on which the component (6) is arranged, and on the connecting lines (11) between the contact pins (8) and the conductor structure (12-12), and f) removing the regions of the conductor layer (4+10) that do not belong to the conductor structure (12-12).

IPC 8 full level

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